



#a Pre Ameble A
10-19-01
exterles

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

SEKO, Toshiharu

Atty. Ref.: 925-214

Serial No. unknown

Group:

Filed: October 12, 2001

Examiner:

For: TAPE FOR CHIP ON FILM AND SEMICONDUCTOR THEREWITH

October 12, 2001

Assistant Commissioner for Patents Washington, DC 20231

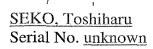
Sir:

PRELIMINARY AMENDMENT

Please amend the above-identified application as follows:

IN THE CLAIMS

Please substitute the following amended claim 18 for the corresponding claim 18 previously presented. A copy of the amended claim 18 showing current revisions is attached.







18. A semiconductor device comprising a semiconductor element mounted on the tape for chip on film as defined in Claim 1 and sealed with resin.

HWB:ecb

1100 North Glebe Road, 8th Floor

Arlington, VA 22201-4714 Telephone: (703) 816-4000 Facsimile: (703) 816-4100

SEKO, Toshiharu Serial No. <u>unknown</u>





REMARKS

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page/s is/are captioned "Version With Markings To Show Changes Made."

Respectfully submitted,

NIXON & VANDERHYE P.C.

By:

H. Warren Burnam, Ir.

Reg. No. 29,366